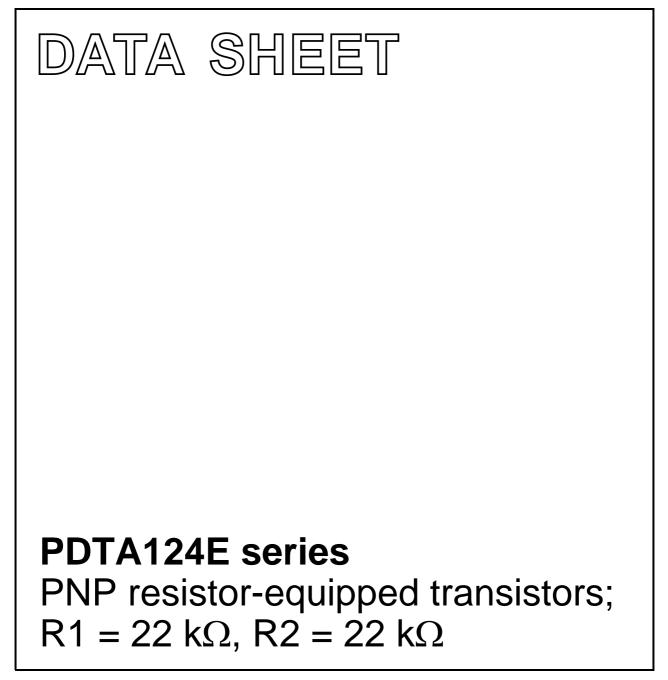
DISCRETE SEMICONDUCTORS



Product data sheet Supersedes data of 2003 Apr 14 2004 Aug 02



## **PDTA124E series**

#### FEATURES

- · Built-in bias resistors
- Simplified circuit design
- Reduction of component count
- Reduced pick and place costs.

#### APPLICATIONS

- · General purpose switching and amplification
- Inverter and interface circuits
- Circuit driver.

**PRODUCT OVERVIEW** 

### QUICK REFERENCE DATA

SYMBOL	PARAMETER	TYP.	MAX.	UNIT
V <sub>CEO</sub>	collector-emitter voltage	-	-50	V
lo	output current (DC)	-	-100	mA
R1	bias resistor	22	-	kΩ
R2	bias resistor	22	-	kΩ

### DESCRIPTION

PNP resistor-equipped transistor (see "Simplified outline, symbol and pinning" for package details).

	PACKAGE				
TYPE NUMBER	PHILIPS	EIAJ	MARKING CODE	NPN COMPLEMENT	
PDTA124EE	SOT416	SC-75	05	PDTC124EE	
PDTA124EEF	SOT490	SC-89	3R	PDTC124EEF	
PDTA124EK	SOT346	SC-59	05	PDTC124EK	
PDTA124EM	SOT883	SC-101	DH	PDTC124EM	
PDTA124ES	SOT54 (TO-92)	SC-43	TA124E	PDTC124ES	
PDTA124ET	SOT23	_	*05 <sup>(1)</sup>	PDTC124ET	
PDTA124EU	SOT323	SC-70	*05 <sup>(1)</sup>	PDTC124EU	

#### Note

- 1. \* = p: Made in Hong Kong.
  - \* = t: Made in Malaysia.
  - \* = W: Made in China.

# PDTA124E series

## SIMPLIFIED OUTLINE, SYMBOL AND PINNING

	SIMPLIFIED OUTLINE AND SYMBOL		PINNING		
TYPE NUMBER			DESCRIPTION		
PDTA124ES	$\begin{bmatrix} 1 \\ \vdots 2 \\ \vdots 3 \end{bmatrix} \begin{bmatrix} 1 \\ \vdots \\ \vdots \\ MAM338 \end{bmatrix} \begin{bmatrix} R_1 \\ R_2 \\ \vdots \\ MAM338 \end{bmatrix}$	PIN 1 2 3	DESCRIPTION base collector emitter		
PDTA124EE PDTA124EEF PDTA124EK PDTA124ET PDTA124EU	$\begin{array}{c} & 3 \\ \hline \\ 1 \\ \hline \\ Top view \end{array}$	1 2 3	base emitter collector		
PDTA124EM	2 1 Bottom view MDB267 3 1 R1 R1 R2 MDB267	1 2 3	base emitter collector		

## PDTA124E series

#### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	-50	V
V <sub>CEO</sub>	collector-emitter voltage	open base	-	-50	V
V <sub>EBO</sub>	emitter-base voltage	open collector	-	-10	V
VI	input voltage				
	positive		-	+10	V
	negative		-	-40	V
I <sub>O</sub>	output current (DC)		-	-100	mA
I <sub>CM</sub>	peak collector current		-	-100	mA
P <sub>tot</sub>	total power dissipation	$T_{amb} \le 25 \ ^{\circ}C$			
	SOT54	note 1	-	500	mW
	SOT23	note 1	-	250	mW
	SOT346	note 1	-	250	mW
	SOT323	note 1	-	200	mW
	SOT416	note 1	-	150	mW
	SOT490	notes 1 and 2	_	250	mW
	SOT883	notes 2 and 3	-	250	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		-	150	°C
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C

#### Notes

- 1. Refer to standard mounting conditions.
- 2. Reflow soldering is the only recommended soldering method.
- 3. Refer to SOT883 standard mounting conditions; FR4 with 60 µm copper strip line.

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-a</sub>	thermal resistance from junction to ambient	in free air		
	SOT54	note 1	250	K/W
	SOT23	note 1	500	K/W
	SOT346	note 1	500	K/W
	SOT323	note 1	625	K/W
	SOT416	note 1	833	K/W
	SOT490	notes 1 and 2	500	K/W
	SOT883	notes 2 and 3	500	K/W

#### Notes

- 1. Refer to standard mounting conditions.
- 2. Reflow soldering is the only recommended soldering method.
- 3. Refer to SOT883 standard mounting conditions; FR4 with 60  $\mu$ m copper strip line.

# PDTA124E series

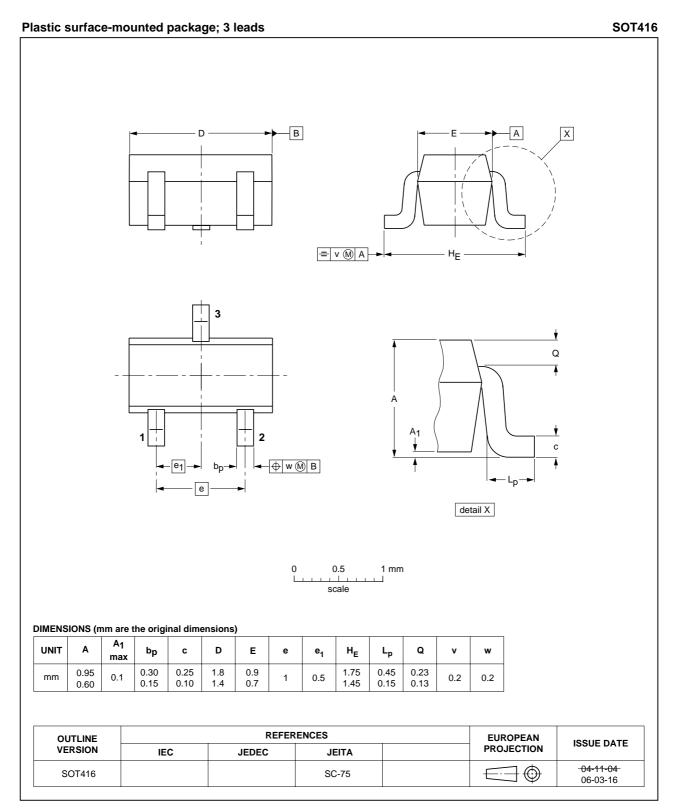
#### CHARACTERISTICS

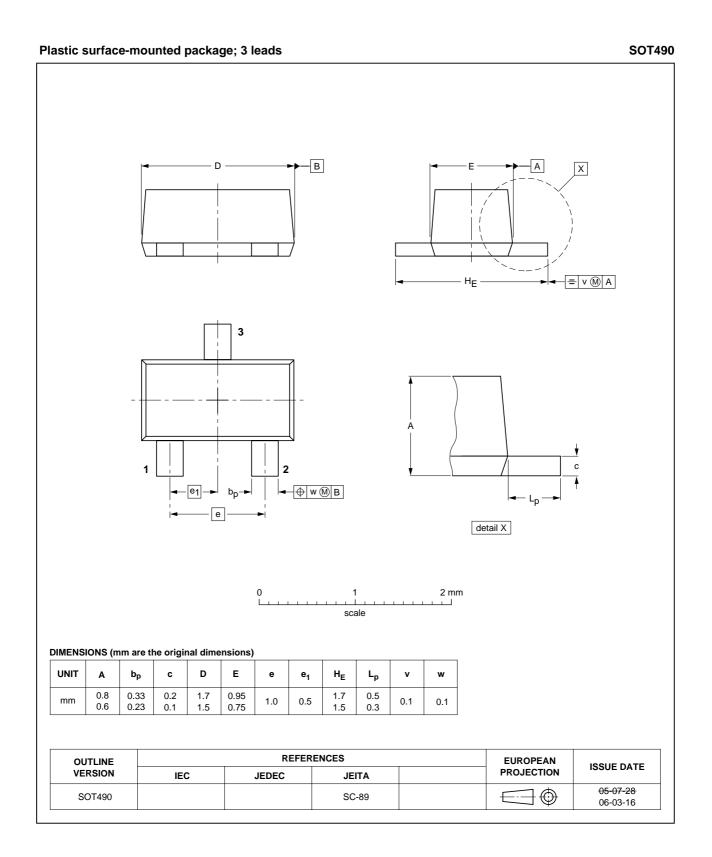
 $T_{amb}$  = 25 °C unless otherwise specified.

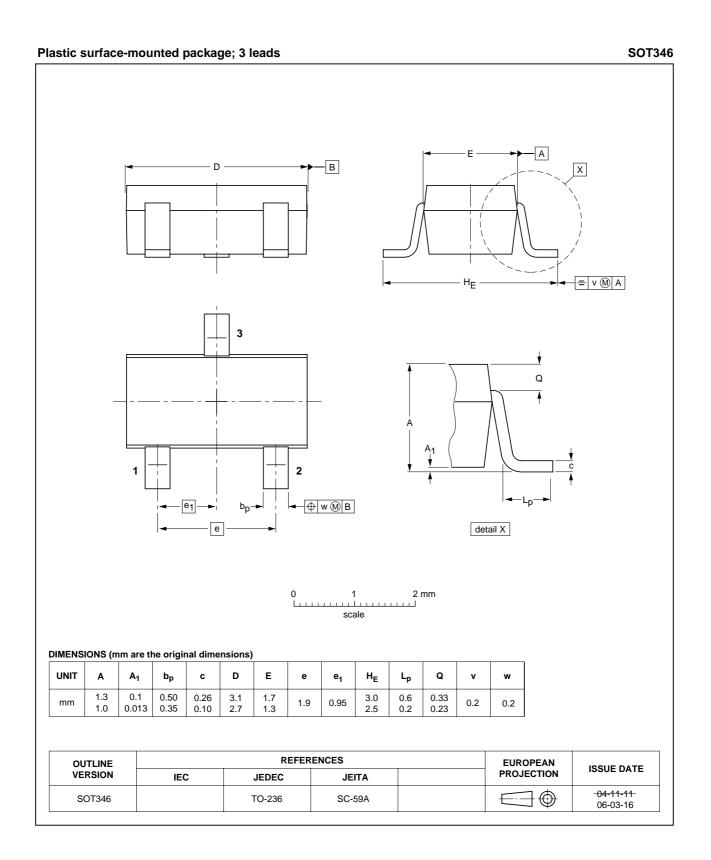
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>CBO</sub>	collector-base cut-off current	$V_{CB} = -50 \text{ V}; I_E = 0$	-	-	-100	nA
I <sub>CEO</sub>	collector-emitter cut-off current	$V_{CE} = -30 \text{ V}; I_B = 0$	-	-	-1	μA
		$V_{CE} = -30 \text{ V}; I_B = 0; T_j = 150 \text{ °C}$	-	-	-50	μA
I <sub>EBO</sub>	emitter-base cut-off current	$V_{EB} = -5 \text{ V}; \text{ I}_{C} = 0$	_	-	-180	μA
h <sub>FE</sub>	DC current gain	$V_{CE} = -5 \text{ V}; \text{ I}_{C} = -5 \text{ mA}$	60	-	-	
V <sub>CEsat</sub>	collector-emitter saturation voltage	$I_{\rm C} = -10$ mA; $I_{\rm B} = -0.5$ mA	_	-	-150	mV
V <sub>i(off)</sub>	input-off voltage	$I_{C} = -100 \ \mu A; \ V_{CE} = -5 \ V$	-	-1.1	-0.8	V
V <sub>i(on)</sub>	input-on voltage	$I_{C} = -5 \text{ mA}; V_{CE} = -0.3 \text{ V}$	-2.5	-1.7	-	V
R1	input resistor		15.4	22	28.6	kΩ
<u>R2</u> R1	resistor ratio		0.8	1	1.2	
C <sub>c</sub>	collector capacitance	I <sub>E</sub> = i <sub>e</sub> = 0; V <sub>CB</sub> = -10 V; f = 1 MHz	_	-	3	pF

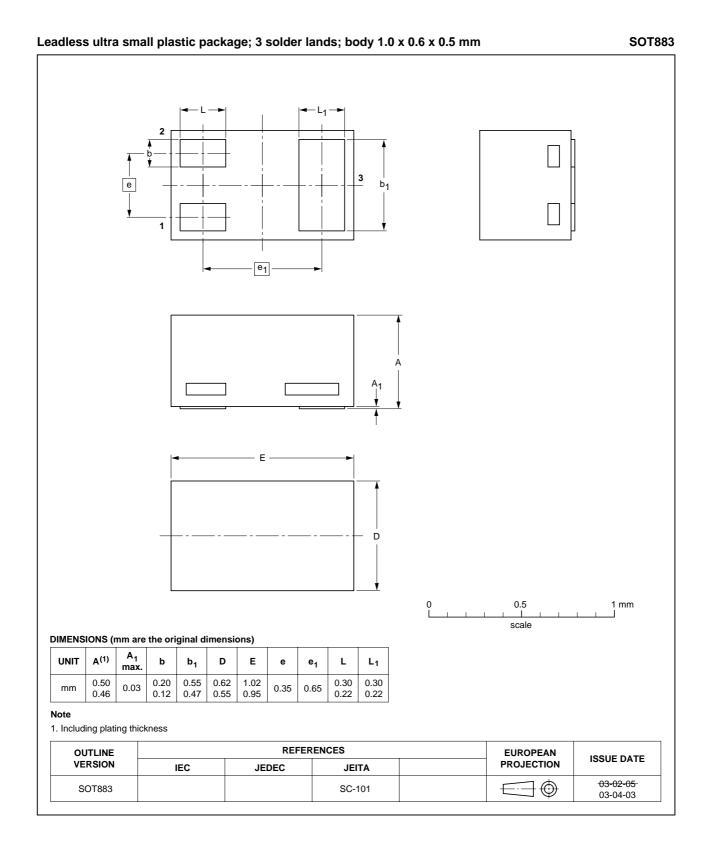
## PDTA124E series

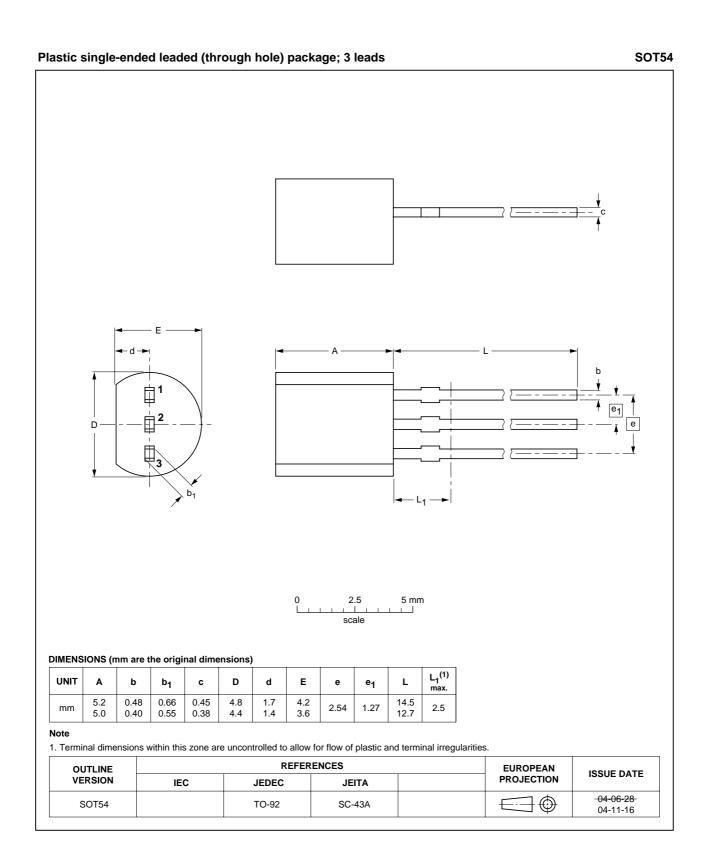
#### PACKAGE OUTLINES

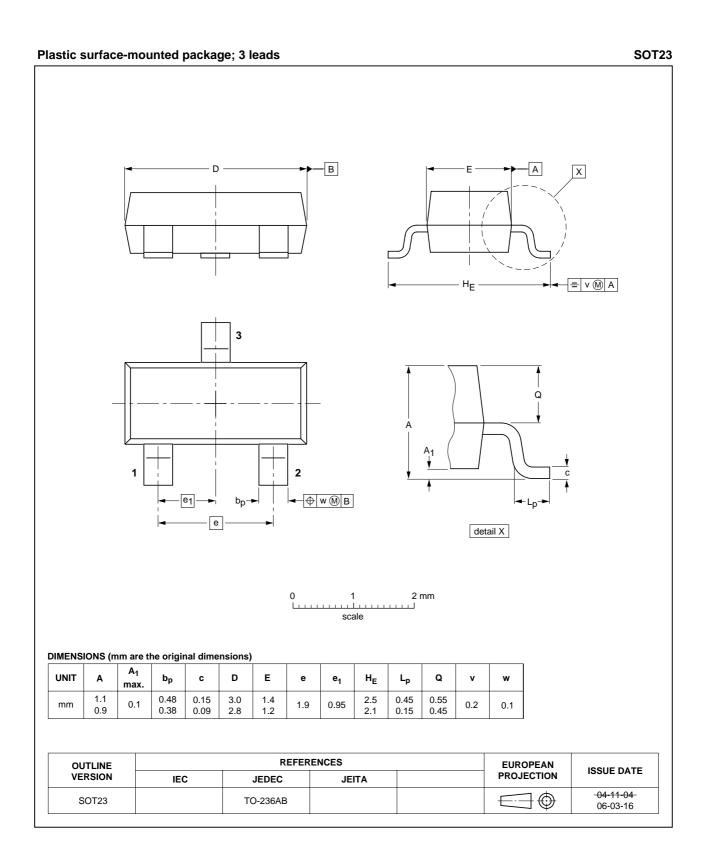


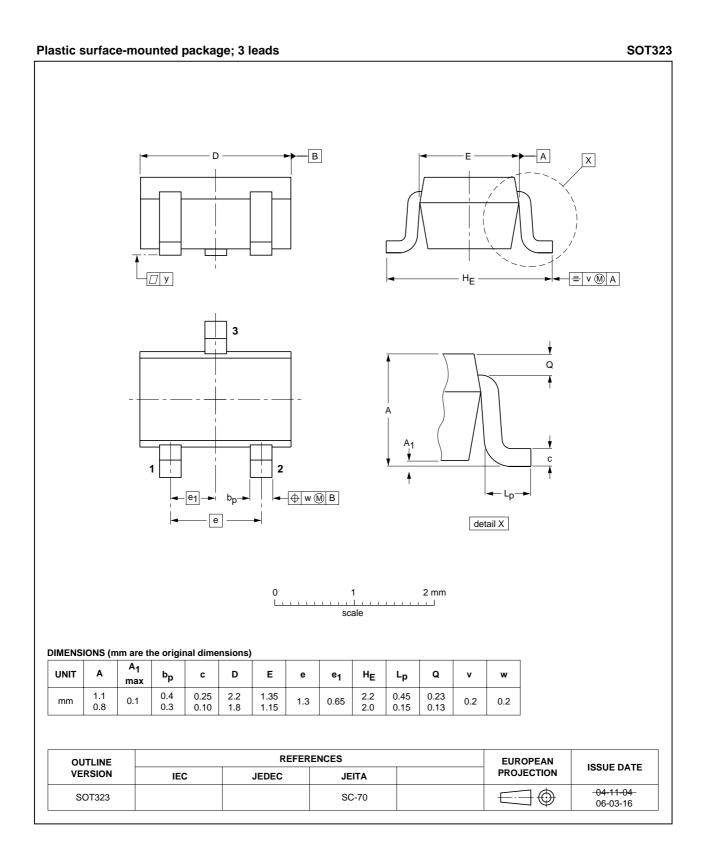












## PDTA124E series

#### DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

#### Notes

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# **NXP Semiconductors**

#### **Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

#### **Contact information**

For additional information please visit: http://www.nxp.com For sales offices addresses send e-mail to: salesaddresses@nxp.com

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